

WHAT IS CLAIMED IS:

1. A chuck table for holding under suction a front side of a wafer which has a device region including a plurality of devices, each having a plurality of electrode bumps, formed in a plurality of areas demarcated in a grid pattern, and an outer peripheral extra region surrounding the device region, comprising:

a holding surface for facing the electrode bumps and holding under suction the device region of the wafer;

a sheet member covering the holding surface;

an outer peripheral extra region support surrounding the holding surface and including an O-ring and an O-ring retainer, the O-ring projecting beyond the holding surface for supporting the outer peripheral extra region of the wafer;

the sheet member extending between the O-ring and the wafer and being secured between the O-ring retainer and an annular sheet member holder;

wherein the O-ring retainer and the O-ring adjust the height of the O-ring so that the O-ring projects from the holding surface by a distance corresponding to the height of the electrode bumps.